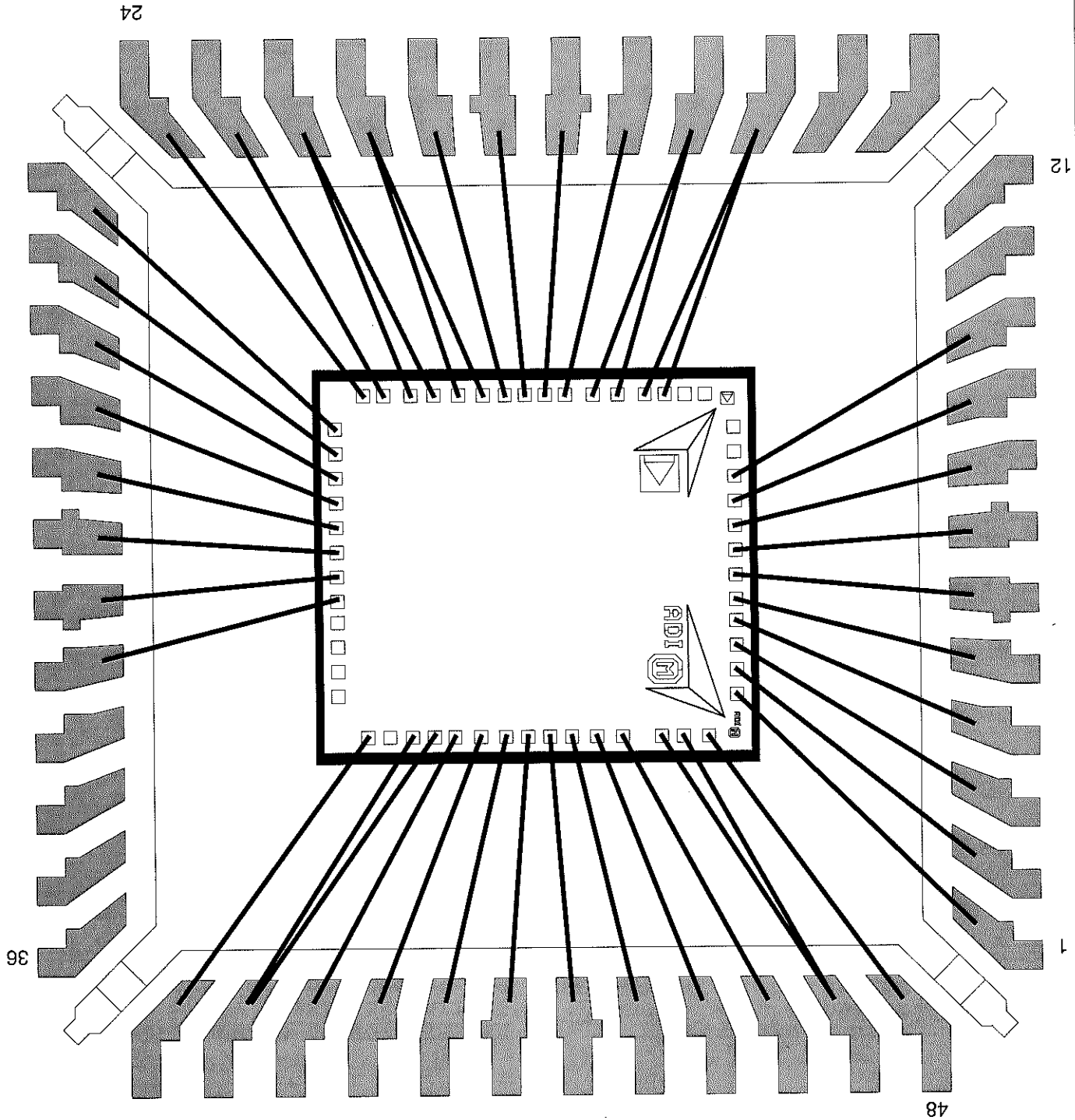


All information in this diagram is proprietary to ANALOG DEVICES INC. and is subject to non-disclosure agreements.
Min. Pad Size
92 x 92 μ m
3.6 x 3.6 mils
Bond Pad Metal Composition
98.5%Al, 1%Si, 0.5%Cu





BD000747

Revision
A

Die Size
3090 x 2750 μ m
122 X 108 mils

Pin to bond first

Scale
25X

CODE IDENT NO
24355

ADIBOND Ver: 5.0
Package Ver: 668.1
RSTC

Foundry Number
PKG000668_A

Paddle Size
5340 x 5340 μ m
210 x 210 mils

48L LQFP 7x7mm

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Min. Pad Size
92 x 92 μ m

3.6 x 3.6 mils

Bond Pad Metal Composition
98.5%Al, 1%Si, 0.5%Cu

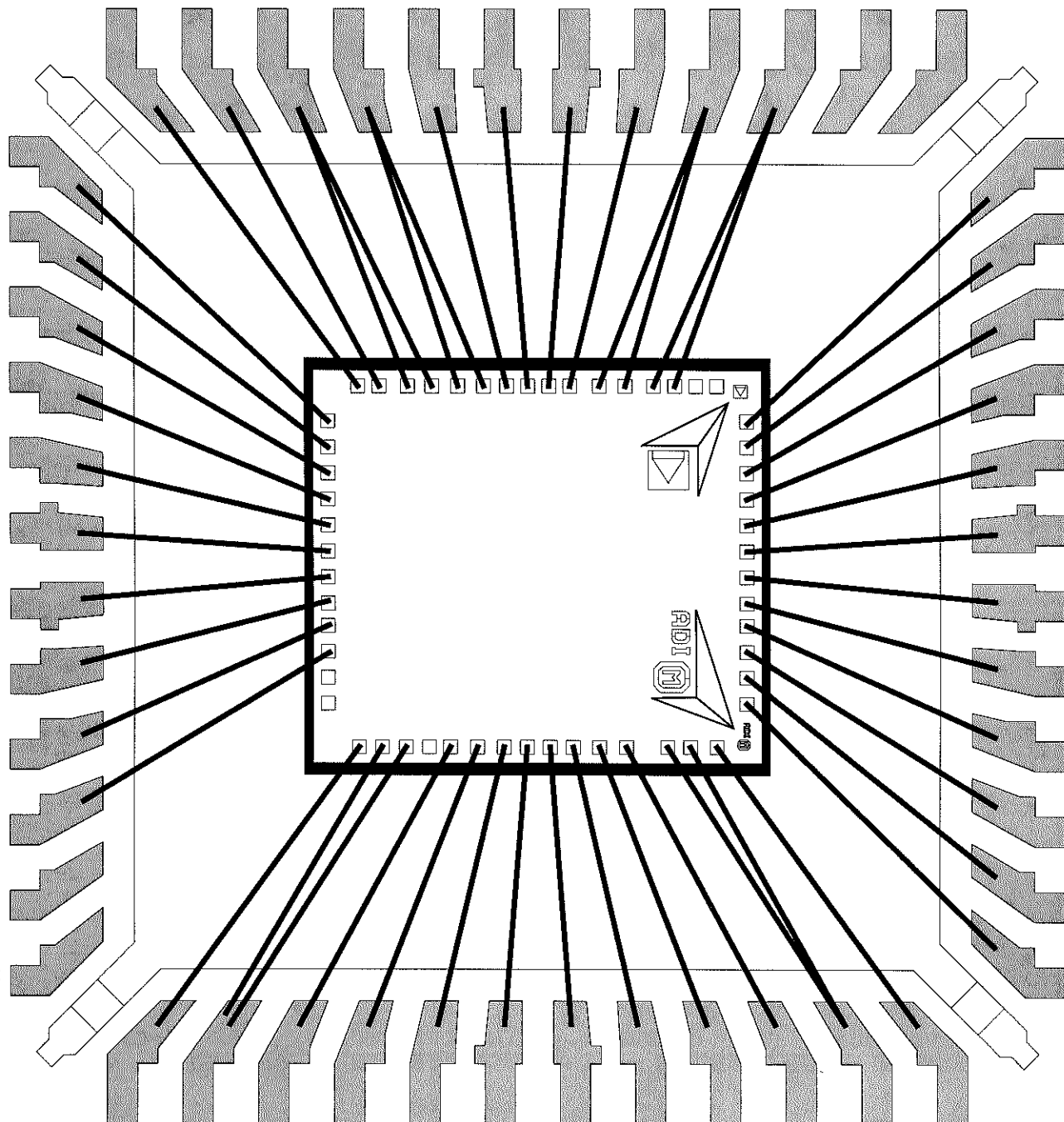
24

12

1

48

36



MANUF. SITE: STAS

PRODUCT: 9765